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Topics of interest include, but are not limited to:

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- Photonic Devices
- Printed Circuit Boards
- Surface-Mount Assemblies
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- System Test

Test Systems
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- Built-in Self-Test
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"NEW FRONTIERS IN TESTING"

International Test Conference is the major forum for the exchange of information about the testing of electronic devices, assemblies and systems. This year the conference focuses on the test techniques and equipment needed to meet the challenges of new technologies. Technical paper sessions, panel discussions, informal evening sessions and a poster session will be presented. An exhibit of the latest equipment and computer aids for testing runs concurrently. There are also two days of test-related tutorials.

Authors are invited to submit original, unpublished papers for presentation at the conference. Submissions for technical paper sessions may be either a summary of at least 500 words or a full manuscript of no more than 12 pages in published format, including figures. The summary is required for the poster session.

Paper selection is highly competitive, so you must clearly describe the nature of the work, its significance to the field of testing, any new or novel features and its status.

All submissions must include:
- title of the paper
- full name of each author (indicating speaker), affiliation, mailing address and telephone number
- an abstract of no more than 35 words

Submissions not meeting these requirements will not be accepted.

Twelve (12) copies of submissions are required and should be sent to the appropriate person listed below according to geographic region.

Deadlines for technical paper submission are:

January 25, 1988 in Europe and India.
February 8, 1988 in U.S.A., Canada, Asia and elsewhere.

Poster session submissions are due by March 15, 1988.

Authors will be notified by April 22, 1988. Final camera-ready full manuscripts and IEEE Copyright Release forms must be received by June 13, 1988.

Suggestions for special sessions or panels are welcome. They should be submitted to the Program Chair by December 15, 1987.

Questions not relating to the Technical program should be addressed to the Executive Secretary.

In U.S.A., Canada and elsewhere
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